

55. The method as recited in claim 35, wherein disposing solder comprises using a squeegee positioned adjacent to the surface of the conveyor belt to deposit solder within the receptacles.
56. The method as recited in claim 35, wherein disposing solder within the plurality of receptacles comprises disposing solder within non-wettable receptacles.
57. The method as recited in claim 35, wherein disposing solder within the plurality of receptacles comprises disposing solder within receptacles of uniform volume.
58. The method as recited in claim 35, wherein disposing solder within the plurality of receptacles comprises disposing solder within receptacles of uniform size.
59. The method as recited in claim 35, wherein each of the plurality of receptacles have a width greater than a diameter of the solder ball formed within each respective receptacle.
60. The method as recited in claim 35, wherein the conveyor belt comprises one of stainless steel and titanium.
61. The method as recited in claim 35, wherein heating the solder disposed within the receptacles comprises moving the conveyor belt along a given path through a furnace.

62. The method as recited in claim 35, further comprising cleaning the solder balls with a cleaning device positioned downstream of the heating device.
63. The method as recited in claim 35, further comprising transferring the solder balls from the conveyor belt to a catch basin positioned downstream of the heating device.
64. The method as recited in claim 35, further comprising removing the solder balls from the conveyor belt.
65. The method as recited in claim 64, wherein removing the solder balls comprises vibrating the conveyor belt to discharge the solder balls from the conveyor belt.